1. INTRODUCTION

This instruction sheet covers the use of the SAMTEC XCede HD Backplane Receptacle Extraction Tool CAT-EX-HDTF-X-XX. This tool assists in the removal of the HDTF-RA connector from a PCB. This tool can only be used once the metal stiffener has been removed. Please reference the instructions for CAT-RE-HDTF-X for further details.

2. CUSTOMER SERVICE

Further tooling and product application assistance is available by contacting the **Samtec Application Service Line +1-800-726-8329 (+1-812-944-6733)** 8:00 AM to 5:00 PM EST. To expedite your inquiry, have the pertinent part numbers for the product and tooling.

3. DESCRIPTION

Each tool has the side marked with the tooling number. Make sure it matches the tooling number specified in this document.

4. REMOVAL

The following steps are recommended for removing the HDTF-RA from a PCB:

1. Prior to removing modules, remove stiffener and confirm that the correct tool PN is being used for the product being removed.

2. Push down on the shoulder bolt to release the sliding arm, and pull sliding arm until it is in the full open position (**Figure 1**). Slide tool around the module to be removed and push the sliding arm in until it reaches full closed position (**Figure 2**). The spring-loaded shoulder bolt should now be locked in place. Ensure that the tool is not overlapping any adjacent modules, or other connector components.

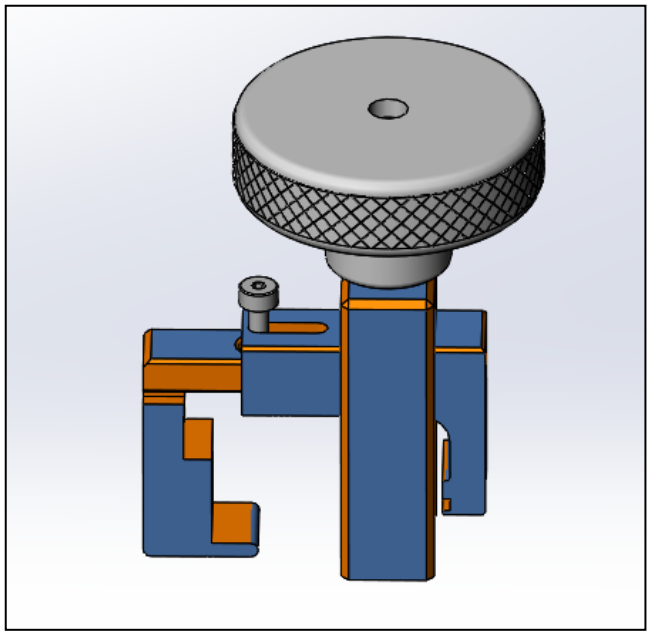

FIGURE 1

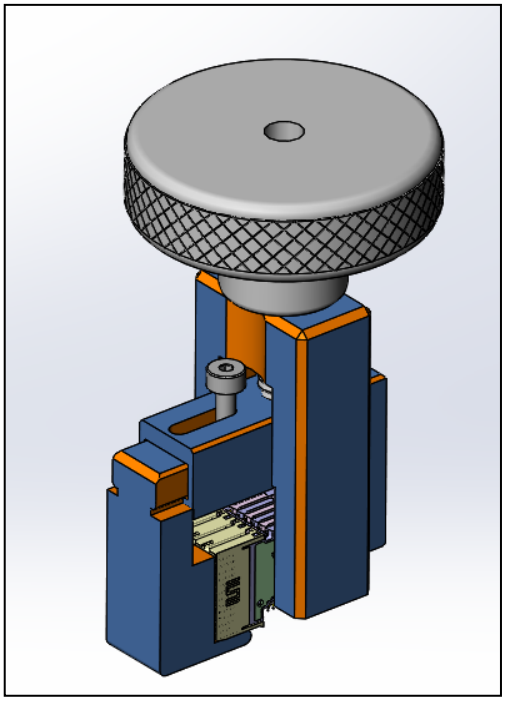

FIGURE 2

3. Turn knob counterclockwise until connector module is full removed from board. To release the module from the tool, turn the knob clockwise or push the spring loaded shoulder bolt to extend the arm.

4. If removing an end connector, use the required extension for removing the connector. This tool does not require an extension is removing a single module.

NOTE: This tool has three configurations to be used with different arrangements of modules on the board. One configuration, using the 'Push Off Board' part, is designed to remove a single daughtercard module with no modules adjacent to it (see Figure 2). The second configuration, using the 'Push Off DC Modules' part, is designed to remove a single daughtercard module with other modules to either side of it (see Figure 3). The third configuration, using the 'Push Off DC Modules' and 'Leg Insert Block' parts, is designed to remove a single daughtercard module with another daughtercard module to only one side of it (see Figure 4). The 'Push Off DC Modules' and 'Push Off Board' parts can be interchanged by unscrewing the tool knob entirely and pulling off the part to be replaced. When utilizing the 'Push Off DC Modules, be sure to orient the part on the removal tool so that the lip in the part will not crush the daughtercard module shoulder.

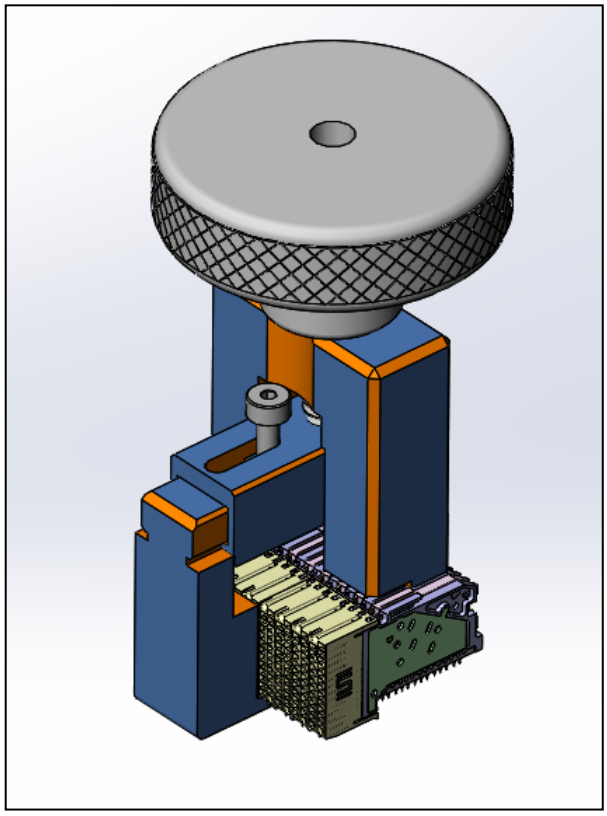

FIGURE 3

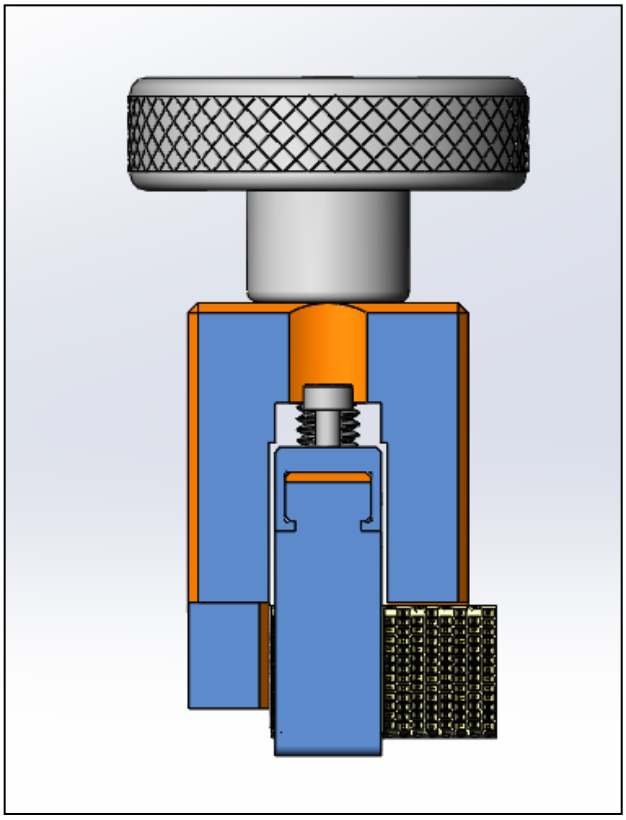

FIGURE 4